

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listing, of claims in the application.

Listing of the Claims:

1. (Currently amended) A material for use in covering objects for microwave heating comprising a substrate substantially transparent to microwave radiation bearing an array of low emissivity metal patch elements defining a frequency selective surface adapted to pass microwave radiation and reflect thermal infrared radiation, the characteristic dimension of said patch elements being no greater than about ~~1600~~500 μm , the average spacing between said patch elements being no greater than about $200\mu\text{m}$ and the combined emissivity of the substrate and patch elements being no greater than about 0.8 in the thermal infrared waveband.
2. (Original) A material according to claim 1 wherein said array is substantially transparent to radiation in the region of 2.45 GHz.
3. (Currently amended) A material according to claim 1 wherein the ~~characteristic dimension of said patch elements is no greater than about $500\mu\text{m}$ and the average spacing between said patch elements is no greater than about $100\mu\text{m}$~~
4. (Previously presented) A material according to claim 1 wherein the combined emissivity of the substrate and patch elements is no greater than about 0.4 in the thermal infrared waveband.
5. (Original) A material according to claim 4 wherein the combined emissivity of the substrate and patch elements is no greater than about 0.2 in the thermal infrared waveband.
6. (Previously presented) A material according to claim 1 wherein said substrate comprises a film of polyester, polypropylene, polyethylene or nylon.

7. (Previously presented) A material according to claim 1 wherein said patch elements are composed of aluminium, copper, gold, titanium or chromium.
8. (Previously presented) A material according to claim 1 wherein said patch elements are in the shape of squares, rectangles, hexagons, circles or crosses.
9. (Previously presented) A packaging material for microwavable foodstuff comprising a material according to claim 1.
10. (Previously presented) A package for microwavable foodstuff comprising a material according to claim 1.
11. (Previously presented) A packaged microwavable foodstuff wherein the package comprises a material according to claim 1.
12. (Previously presented) A bandage or patch adapted to be worn on the body comprising a material according to claim 1.
13. (Previously presented) A method of heating an object which comprises covering the object with a material according to claim 1 and exposing the material to microwave radiation.
14. (Previously presented) A method of manufacturing a material according to claim 1 which comprises: taking a material comprising a substrate substantially transparent to microwave radiation upon which is vacuum deposited a continuous metal foil; applying an etch-resistant substance to the metal foil in patches corresponding to said array; and chemically etching away the metal exposed between the patches of etch-resistant substance.
15. (Previously presented) A method of manufacturing a material according to claim 1 which comprises vacuum depositing a metal onto a substrate substantially transparent to microwave radiation through a mask with a pattern corresponding to said array.

16. (Previously presented) A method of manufacturing a material according to claim 1 which comprises: taking a material comprising a metal foil with a heat-sensitive adhesive backing; bonding said foil to a substrate substantially transparent to microwave radiation with a heated stamp having a pattern corresponding to said array; and removing the portions of said foil left unbonded by said stamp.